

XP-002245768

AN - 1974-23748V [13]

A - [001] 012 04- 041 046 047 061 062 063 231 239 255 332 398 444 47& 477
688

CPY - SHIU

DC - A97 E13 M23

FS - CPI

MC - A12-W12 E07-D09 M23-A02

M3 - [01] M282 M283 M210 M211 M212 M213 M214 M215 M216 M220 M221 M222 M223
M224 M225 M226 M231 M232 M233 M240 M281 M311 M312 M313 M314 M315 M316
M320 F523 H603 H608 H600 Q130 M510 M521 M530 M540 Q467 M781 R043 M413
M902

PA - (SHIU) SHIKOKU-KASEI KOGYO CO

PN - JP48085458 A 19731113 DW197413 000pp

PR - JP19720017500 19720217

AB - J48085458 A flux compn. contains a high-mol. wt. polymer and imidazole
cpd. (I) or (II) where R is a long-chain alkyl, R' and R'' are H, lower
alkyl, or halogen, and HA is an org or inorg. acid. The flux compn.
may also contain a rosin. In an example a low d.p. polyethylene film
(Parafilm M) 10, 2-undecyl-4-methyl-5-bromoimidazole 3, and maleic
anhydride-denatured rosin (J896) 6 g were added to turpentine oil 200
ml and stirred in a water bath for 2 hr. Cu wires were passed through
the soln. dried, coated with a vinyl chloride resin at 180 degrees,
and peeled. The exposed portion was dipped in a solder bath at 260
degrees, and the Cu wire was covered by the solder.

IW - COPPER WIRE SOLDER FLUX CONTAIN HIGH MOLECULAR WEIGHT POLYMER
IMIDAZOLE COMPOUND OPTION ROSIN

IKW - COPPER WIRE SOLDER FLUX CONTAIN HIGH MOLECULAR WEIGHT POLYMER
IMIDAZOLE COMPOUND OPTION ROSIN

NC - 001

OPD - 1972-02-17

ORD - 1973-11-13

PAW - (SHIU) SHIKOKU-KASEI KOGYO CO

TI - Copper wire soldering flux - contains high molecular weight polymer an
imidazole cpd. and opt. a rosin